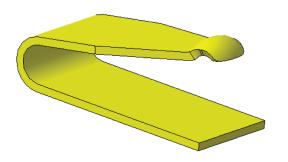
Pulse Part Number W9908





1

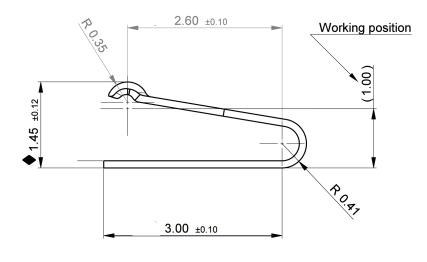
Ideal for board-to-antenna applications Spring contact for positive connection Surface mount technology; solder reflowable

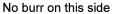
Features

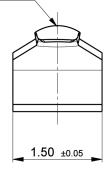
- PWB Footprint 3.2 x 1.7 mm
- Nominal Contact Height 1 mm
- Tape & Reel Packaging
- RoHS Compliant Product

Applications

- Antenna Contacts



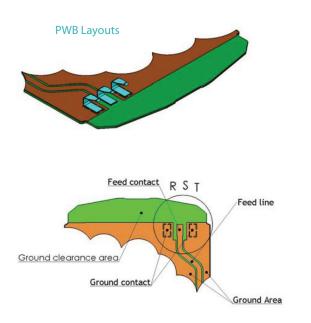




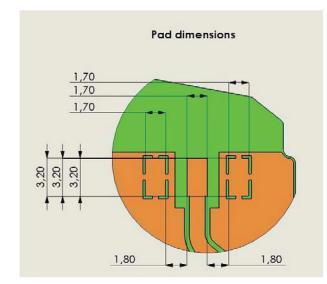
San Diego, CA 858 674 8100 Vancouver, WA 360 944 7551 Europe 49 7032 7806 0 Asia 86 755 33966678 North Asia 886 3 4356768 China 86 512 6807 9998

Pulse Part Number W9908

W9908 C-Clip Configuration and Dimensions

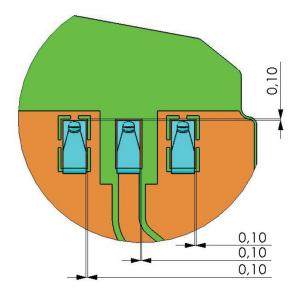


Ground Clearance Area for W9908 C-Clip



PWB Footprint Dimensions and C-Clip Position for W9908

C-clip position on PWB layout





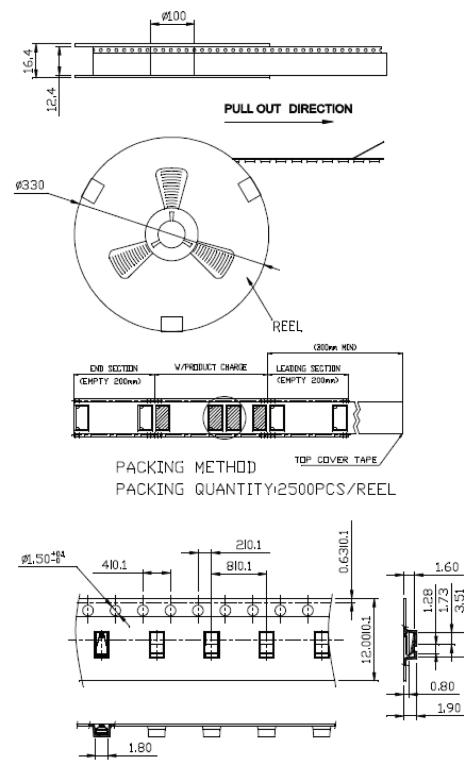
Ground clearance area

0,20 1 Feed pad with 1mm GND clearance area 1 . 0,20 0,50 3,60 2,10 3ND pads with 0,2mm clearances 0,50 DETAIL R SCALE 5 : 1

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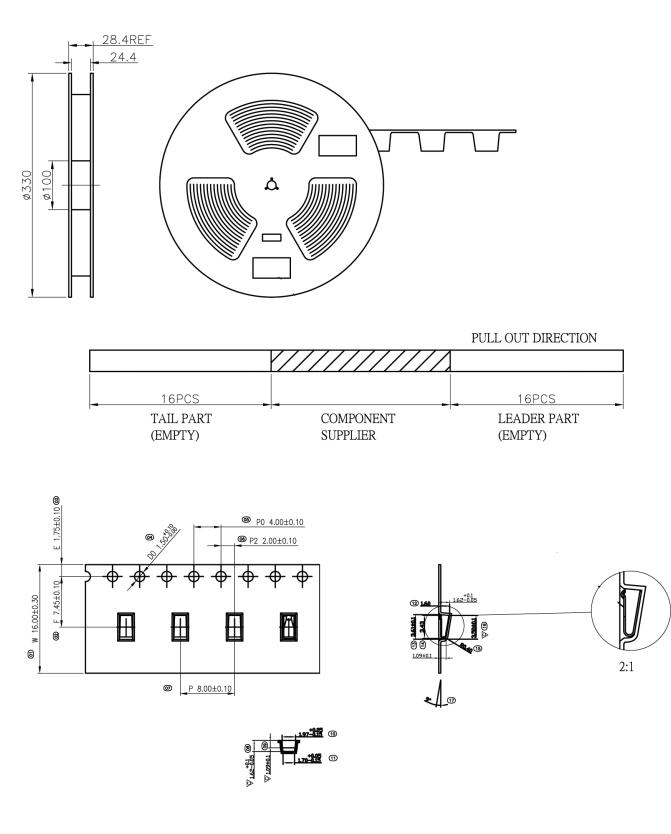
Pulse Part Number W9908







Pulse Part Number W9908





Pulse Part Number W9908

W9908 Connector Soldering

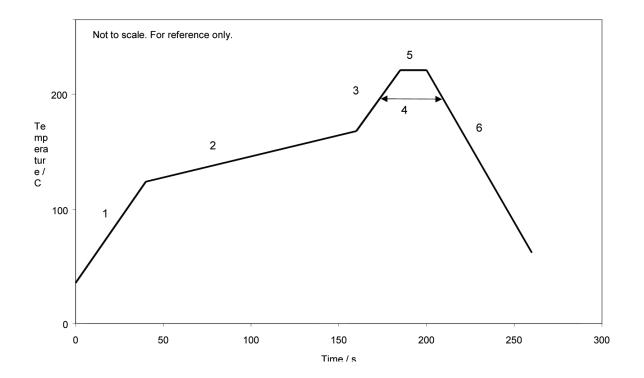
Recommendation for reflow soldering process

Printing stencil thickness 0.15 to 0.25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C.

The temperature profile recommendations for reflow solder process are presented in Figure 1 and 2. The reflow profile presented in Figure 2 describes maximum reflow temperatures.

Figure 1 - Minimum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 30 sec
5	Peak temperature in reflow	230°C for 10 seconds
6	Temperature gradient in cooling	Max -5°C/s

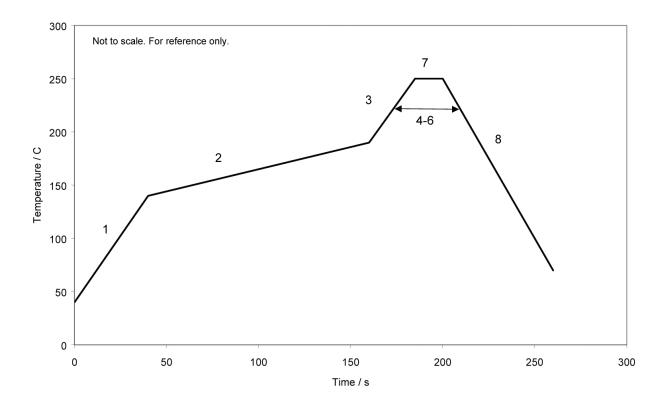




Pulse Part Number W9908

Figure 2 - Maximum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 60 sec
5	Time above 230°C	Max 50 sec
6	Time above 250°C	Max 10 sec
7	Peak temperature in reflow	260°C for 5 seconds
8	Temperature gradient in cooling	Max -5°C/s





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